

ANGULAR TOL	±	0.5 °	EC NO:
4 PLACES	±		DRWN:
3 PLACES	±		CHK'D:
2 PLACES	±	0.15	APPR:
1 PLACE	±	0.25	INITIA DRWN:
0 PLACES	±		APPR:
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MA	TING	PROFI	ILE			<b>t</b>				J
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AP: LCP L TAINLESS	S STÉEL									F
CONDUCTIVE COPPER ALLOY ACTS: 0.75 MICRON MIN GOLD OVER 1.27 MICRON MIN NICKEL 3.18 MICRON MIN SILVER OVER 1.27 MICRON MIN NICKEL DARD PIN DRAWINGS E BASED ON 1.58MM BOARD THICKNESS): VING 2032633080-SD, MIN. MATING DISTANCE 6.7MM T DRAWING 2032630001-SD, MIN. MATING DISTANCE 6.9MM 40UNT DRAWING 2032634185-SD, MIN. MATING DISTANCE 9.9MM										E
CATION: 2043130001-PS CIFICATION: 2043130001-AS SPEC FOR SOLDERING INFORMATION FICATION: 2043650000-PK NTS WILL BE SUPPLIED TARNISH FREE OVER TIME. AP TO BE REMOVED AFTER SOLDERING.									D	
LASER MARKED APPROXIMATELY WHERE SHOWN MAT ON THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSI EENT REV DESC: UPDATED THE TITLE BLOCK									ERMISSIO	N C
O: 747243 N: SACHIK7 2023/02/28 D: SCS02 2023/04/25 R: HTHYAGARAJ 2023/04/26 PRODUCT CUSTOMER DRAWING									E	
AL REVISION: DOC TYPE DOC PART REVISION: 2019/10/03 2121955010-SD PSD 000 B							B3			
	DRAWING	series 212195	MATERIAL NUM		CUSTOMER GENERA	AL MA	RKET		OF 1	A